

REMARKS

Applicants respectfully traverse and request reconsideration.

The Restriction Requirement dated January 29, 2002 alleges that Claims 1-20 drawn to a semiconductor device and Claims 21-27 drawn to a process of fabricating an integrated circuit are allegedly distinct. The Restriction Requirement alleges that the device of the Group I invention could be made by processes materially different from that of the Group II invention. The Office Action states "for example, instead of thermally coupling the first substrate to the second substrate such that during operation of the integrated circuit, the second substrate thermally conducts heat generated by the at least one heat generating circuit away from the at least one heat generating circuit, the first substrate thermally coupled to the second substrate, such that, after operation of the integrated circuit, the second substrate thermally conducts heat generated by the at least one heat generating circuit away from the at least one heat generating circuit." Applicants' attorney is confused by this statement. Applicants' attorney attempted to reach Examiner Williams by telephone. The message on the Examiner's telephone indicated that the Examiner will be out until March 6, 2002. Accordingly, Applicants' attorney was not able to get clarification by telephone. It appears that the statement does not provide any process that is materially different from that set forth, for example, in Group II. The only differing words appear to be "after operation" as opposed to "during operation". As best understood, such a process is not materially different.


Accordingly, Applicants respectfully request withdrawal of the Restriction Requirement.

In any event, Applicants have suitably amended Claim 22 so that the distinction made by the Examiner is no longer applicable.

Attached hereto is a marked-up version of the changes made to Claim 21 by the current amendment. The attached page is captioned: "Version with Markings to Show Changes Made."

To the extent necessary, Applicants choose Group I claims, namely Claims 1-20 to be examined at this time.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

21. (Once Amended) A method for fabricating an integrated circuit, the method comprising the steps of:

providing a first substrate, the first substrate including at least one heat-generating circuit and having a first coefficient of thermal expansion;

providing a second substrate, the second substrate having a second coefficient of thermal expansion that is substantially equal to the first coefficient of thermal expansion;

thermally coupling the first substrate to the second substrate, [such that, during operation of the integrated circuit,]the second substrate thermally conducts heat generated by the at least one heat-generating circuit away from the at least one heat-generating circuit.